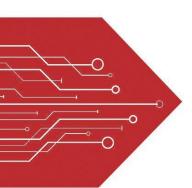
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet







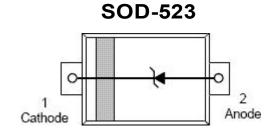


Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Features

- **Small Body Outline Dimensions**
- Low Body Height
- Stand-off Voltage: 2.5 V 12 V
- Peak Power up to 200 Watts @ 8 x 20 _s Pulse
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection
- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



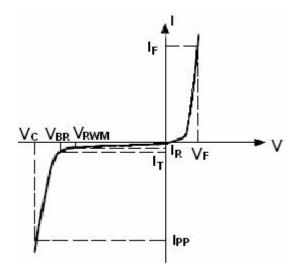
Absolute Ratings (T_{amb}=25°C)

| Symbol | Parameter | Value | Units |
|------------------|---|-------------|-------|
| P _{PP} | Peak Pulse Power (t _p = 8/20μs) | 200 | W |
| TL | Maximum lead temperature for soldering during 10s | 260 | °C |
| T _{stg} | Storage Temperature Range | -55 to +150 | °C |
| T _{op} | Operating Temperature Range | -40 to +125 | °C |
| Tj | Maximum junction temperature | 150 | °C |
| | IEC61000-4-2 (ESD) air discharg contact discharg | | KV |
| | IEC61000-4-4 (EFT) | 40 | Α |
| | ESD Voltage Per Human Body Mode | 16 | KV |



Electrical Parameter

| Symbol | Parameter | | |
|-----------------|--|--|--|
| I _{PP} | Maximum Reverse Peak Pulse Current | | |
| Vc | Clamping Voltage @ IPP | | |
| V_{RWM} | Working Peak Reverse Voltage | | |
| I _R | Maximum Reverse Leakage Current @ V _{RWM} | | |
| I _T | Test Current | | |
| V_{BR} | Breakdown Voltage @ I _T | | |
| I _F | Forward Current | | |
| V _F | Forward Voltage @ I _F | | |



Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

| Device | Device | V _{RWM} (V) | I _R (uA) @ V _{RWM} | V _{BR} (V)@ I _T (Note 1) | Ι _Τ | V _C (V) @ I _{PP} =5 A* | V _C (V) @ Max I _{PP} * | I _{PP} (A)* | P _{PK} (W)* | C (pF) |
|-------------|---------|-------------------------|---|---|----------------|---|---|----------------------|----------------------|-----------|
| | Marking | Max | Max | Min | mA | Тур | Max | Max | Max | Тур |
| ESD5Z2V5-MS | ZD | 2.5 | 6.0 | 4.0 | 1.0 | 6.5 | 10.9 | 11.0 | 120 | 145 |
| ESD5Z3V3-MS | ZE | 3.3 | 1.0 | 5.0 | 1.0 | 8.4 | 14.1 | 11.2 | 158 | 105 |
| ESD5Z5V0-MS | ZF | 5.0 | 1.0 | 6.2 | 1.0 | 11.6 | 18.6 | 9.4 | 174 | 80 |
| ESD5Z6V0-MS | ZG | 6.0 | 1.0 | 6.8 | 1.0 | 12.4 | 20.5 | 8.8 | 181 | 70 |
| ESD5Z7V0-MS | ZH | 7.0 | 1.0 | 7.5 | 1.0 | 13.5 | 22.7 | 8.8 | 200 | 65 |
| ESD5Z12V-MS | ZM | 12 | 1.0 | 13.5 | 1.0 | 17 | 25 | 9.6 | 240 | 55 |

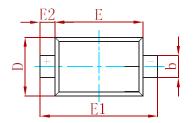
^{*}Surge current waveform per Figure 1.

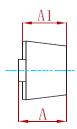
^{1.} V_{BR} is measured with a pluse test current I_T at an ambient temperature of 25 $^\circ\!\!\!\!\!\!\!^\circ$.

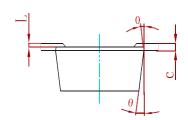




PACKAGE MECHANICAL DATA

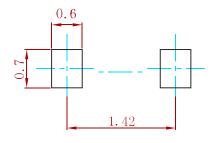






| Cumbal | Dimensions | In Millimeters | Dimensions In Inches | | |
|--------|------------|----------------|----------------------|-------|--|
| Symbol | Min | Max | Min | Max | |
| Α | 0.510 | 0.770 | 0.020 | 0.031 | |
| A1 | 0.500 | 0.700 | 0.020 | 0.028 | |
| b | 0.250 | 0.350 | 0.010 | 0.014 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 0.750 | 0.850 | 0.030 | 0.033 | |
| E | 1.100 | 1.300 | 0.043 | 0.051 | |
| E1 | 1.500 | 1.700 | 0.059 | 0.067 | |
| E2 | 0.200 REF | | 0.008 REF | | |
| L | 0.010 | 0.070 | 0.001 | 0.003 | |
| 0 | 7° REF | | 7° F | REF | |

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|-------------|---------|------|
| ESD5ZXXX-MS | SOD-523 | 3000 |



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